

PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Marcos Karnezos | 05/17/2006 |
| RECEIVING PARTY DATA | |
| Name: | STATS ChipPAC Ltd. |
| Street Address: | 10 Ang Mo Kio Street 65, #05-17/20 Techpoint |
| City: | Singapore |
| State/Country: | SINGAPORE |
| PROPERTY NUMBERS Total: 2 | |
| Property Type | Number |
| Application Number: | 60669975 |
| Application Number: | 11396954 |
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| ATTORNEY DOCKET NUMBER: | CPAC 1090-2 |
| NAME OF SUBMITTER: | Bill Kennedy |
| Total Attachments: 2 | |
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| source=CPAC 1090-2 Assignment 2006-05-17#page2.tif | |

CH \$80.00 60669975

**SOLE TO CORPORATE
ASSIGNMENT**

WHEREAS, the undersigned Marcos Karnezos, hereinafter termed the "Inventor" has invented certain new and useful improvements in:

***Semiconductor Multipackage Module Including Tape Substrate Land Grid Array
Package Stacked Over Ball Grid Array Package***

and has filed a provisional application for United States patent disclosing and identifying the invention, the said provisional application having been filed on 11 April 2005 as U.S. Application No. 60/669,975; and has filed a non-provisional application for United States patent disclosing and identifying the above invention, the non-provisional application having been filed on 03 April 2006 as U.S. Application No. 11/396,954, OR is filing such a non-provisional application herewith; and has executed an oath or declaration of inventorship for such non-provisional application on:

the 17th day of May, 2006,

hereinafter termed the "Applications"; and

WHEREAS, STATS ChipPAC Ltd., a corporation of Singapore, located at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, hereinafter referred to as "Assignee," is desirous of acquiring the entire right, title and interest in and to the Applications and the invention disclosed therein, and in and to any and all embodiments of the invention, heretofore conceived, made, or discovered jointly or severally by said Inventors (all collectively hereinafter termed the "Invention") and in and to any and all patents, inventors' certificates, and other forms of protection (hereinafter termed the "Patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged by the Inventor:

1. The Inventor has assigned to the Assignee, and does hereby sell, assign, transfer and convey to the Assignee all right, title and interest (a) in and to the Invention and the Applications; and (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial designs) on the Invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the Applications; and (c) in and to any and all applications filed and any and all patents granted on the Invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.


2. The Inventor hereby covenants and agrees to cooperate with the Assignee to enable the Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by the Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by the Assignee (a) for perfecting in the Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering the Invention; (d) for filing and prosecuting applications for reissuance of any said Patents; (e) for interference or other priority proceedings involving the Invention; and (f) for legal proceedings involving the Invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use

proceedings, infringement actions and court actions; provided, however, that the expense incurred by the Inventor in providing such cooperation shall be paid for by the Assignee.

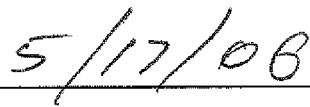
3. The terms and covenants of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representatives, and shall be binding upon the Inventor, his heirs, legal representatives and assigns.

4. The Inventor hereby warrants and represents that he has not entered into and will not enter into any assignment, contract, or understanding in conflict herewith.

IN TESTIMONY WHEREOF, the Inventor has executed and delivered this instrument to the Assignee as of the date written below.



Marcos Karnezos



Date